Application No.: 10/810,700

REMARKS

Claims 1-15 are all the claims pending in the application. Of these, claims 8-13 are withdrawn from consideration.

I. Response to Obviousness-Type Double Patenting Rejections

A. App. Ser. No. 10//123,113 (U.S. Patent No. 7,214,424)

Claims 14 and 15 are rejected on the ground of non-statutory obviousness-type double patenting as being unpatentable over claims 1, 13 and 14 of co-pending Application No. 10/123,113 (US 2002/0192463).

For the record, Applicants note that U.S. App. Ser. No. 10/123,113 has issued as U.S. Patent No. 7,214,424 (May 8, 2007).

Applicants respectfully traverse the rejection and submit that the present invention is not an obvious variant of the subject matter of the issued claims of the '424 patent. Specifically, a characteristic feature of the present invention is that "the heat-expandable pressure-sensitive adhesive layer (b) and the substrate (a) are peelable from each other by heating". This feature is not recited in the claims of the issued '424 patent and there is no motivation for one of ordinary skill in the art to modify the subject matter of the claims of the '424 patent. Thus, the present invention is not an obvious variant of the claims of the '424 patent.

Accordingly, Applicants respectfully request withdrawal of the obviousness-type double patenting rejection.

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B. App. Ser. No. 10/404,861 (U.S. Patent No. 7,163,597)

Claims 1-7 are rejected on the ground of non-statutory obviousness-type double patenting as being unpatentable over claims 1-4 of co-pending Application No. 10/404,861 (US 2003/0203193).

For the record, Applicants note that U.S. App. Ser. No. 10/404,861 has issued as U.S. Patent No. 7,163,597 (January 16, 2007).

Applicants respectfully traverse the rejection and submit that the present invention is not an obvious variant of the subject matter of the issued claims of the '597 patent. Specifically, a characteristic feature of the present invention is that "the heat-expandable pressure-sensitive adhesive layer (b) and the substrate (a) are peelable from each other by heating". This feature is not recited in the claims of the issued '597 patent and there is no motivation for one of ordinary skill in the at to modify the subject matter of the claims of the '597 patent. Thus, the present invention is not an obvious variant of the claims of the '597 patent.

Accordingly, Applicants respectfully request withdrawal of the obviousness-type double patenting rejection.

C. App. Ser. No. 10/415,948

Claims 1-7 are provisionally rejected on the ground of non-statutory obviousness-type double patenting as being unpatentable over claims 1-5 of co-pending Application No. 10/415,948 (US 2004/0038020).

Applicants respectfully defer responding to the provisional obviousness-type double patenting rejection.

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II. Response to Claim Rejection Under 35 U.S.C. § 102

Claims 1-7, 14 and 15 are rejected under 35 U.S.C. § 102(b) as being anticipated by EP

1,154,002 A1 to Kiuchi et al.

Applicants respectfully traverse the rejection.

The present invention is directed to a heat-peelable double-faced pressure-sensitive

adhesive sheet consisting essentially of a substrate (a), a heat-peelable pressure-sensitive

adhesive layer (b) formed on one side of the substrate (a) and containing heat-expandable

microspheres, and a pressure-sensitive adhesive layer (c) formed on the other side of the

substrate (a), wherein the heat peelable pressure-sensitive adhesive layer (b) and the substrate (a)

are peelable from each other by heating.

The present invention is characterized in that peeling occurs between the substrate and

the heat-peelable pressure-sensitive adhesive layer (heat-expandable layer). In this connection it

is submitted that the adhesive layer (b) of the adhesive sheet of the present invention may be

formed by, for example, a method in which a mixture comprising heat-expandable microspheres

and a pressure-sensitive adhesive is applied to the substrate (a). Alternatively, a method may be

employed in which the mixture is applied to an appropriate separator to form the adhesive layer

(b), which is then transferred to the substrate (a). Preferably, the side of the substrate (a) on

which the adhesive layer is applied may have undergone a releasability-imparting treatment prior

to the application of the adhesive layer (specification page 6, lines 22 to 24). This results in the

formation of an adhesive sheet in accordance with claim 1 of the present invention, consisting

essentially of an adhesive layer (b) and a substrate (a) which are peelable from each other by

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heating. Consequently, the adhesive layer and the substrate of the adhesive sheet are separated from each other by heating.

On the other hand, Figure 2 of Kiuchi depicts a substrate 1 with a heat-expandable adhesive layer 2 on one side and an adhesive layer 4 on the other side. The Examiner asserts that Kiuchi discloses that when the heat-expandable microspheres are foamed or expanded by a thermal treatment, the heat-expandable layer changes in volume to form a three-dimensional structure with a rough surface and therefore the adhesive strength decreases significantly. The Examiner concludes that Kiuchi implicitly discloses that the substrate can be peclable from the heat-expandable adhesive layer. See the 1st paragraph at page 5 of the Action dated May 2, 2007.

However, the disclosure relied upon by the Examiner does not support the Examiner's position. That is, in [0047] of EP '002, Kiuchi discloses that:

Furthermore, since the adhesive sheet ahs a heat-expandable layer containing heat-expandable microspheres, the heat-expandable microspheres are promptly foamed or expanded by a heat treatment and the heat-expandable layer changes n volume to form a three-dimensional structure with a rough surface. Consequently, the area in which the adhesive layer is adherent to the cut pieces 7 resulting from the cutting decreases considerably, and the adhesive strength hence decreases greatly... As a result, the operating efficiency and working efficiency in the step of separating and recovering the cut pieces 7 are greatly improved...

Thus, this disclosure teaches separation between an adherend and the heat-expandable adhesive layer, not separation between the heat-expandable adhesive layer and the substrate. In addition, if the heat-expandable adhesive layer separated from the substrate, then the invention of Kiuchi would be inoperative. Thus, Kiuchi does not anticipate the present invention.

Accordingly, Applicants respectfully request withdrawal of the rejection.

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III. Conclusion

In view of the above, reconsideration and allowance of this application are now believed

to be in order, and such actions are hereby solicited. If any points remain in issue which the

Examiner feels may be best resolved through a personal or telephone interview, the Examiner is

kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue

Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any

overpayments to said Deposit Account.

Respectfully submitted,

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Date: July 31, 2007

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